

United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.		
10/613,849	07/03/2003	Leah Markowitz	TSL-101	TSL-101 7262		
22888	7590 10/06/2004		EXAM	EXAMINER		
	OFFMAN & HARMS,	MAI, A	MAI, ANH D			
TRI-VALLE 1432 CONC	EY OFFICE ANNON BLVD., BLDC	ART UNIT	PAPER NUMBER			
LIVERMORE, CA 94550			2814	2814		
			DATE MAILED: 10/06/2004			

Please find below and/or attached an Office communication concerning this application or proceeding.

				(/K	
		Application N	lo.	Applicant(s)	
Office Action Summary		10/613,849		MARKOWITZ ET AL.	
		Examiner		Art Unit	
		Anh D. Mai		2814	
Period f	The MAILING DATE of this communication ap or Reply	opears on the co	er sheet with the o	correspondence addre	ss
THE - Extended after aft	MAILING DATE OF THIS COMMUNICATION ensions of time may be available under the provisions of 37 CFR 1 r SIX (6) MONTHS from the mailing date of this communication. e period for reply specified above is less than thirty (30) days, a re O period for reply is specified above, the maximum statutory period ure to reply within the set or extended period for reply will, by status reply received by the Office later than three months after the mail ned patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, h ply within the statutory d will apply and will exp te, cause the application	owever, may a reply be tir minimum of thirty (30) day ire SIX (6) MONTHS from on to become ABANDONE	mely filed ys will be considered timely. the mailing date of this comm CD (35 U.S.C. § 133).	unication.
Status					
1)⊠ 2a)□ 3)□	This action is FINAL . 2b)⊠ Th Since this application is in condition for allow	is action is non-tance except for	formal matters, pr		erits is
	closed in accordance with the practice under	Ex parte Quayle	e, 1935 C.D. 11, 4	53 O.G. 213.	v
Disposi	tion of Claims				
5) <u>□</u> 6)⊠	Claim(s) 1-14 is/are pending in the application 4a) Of the above claim(s) is/are withdred claim(s) is/are allowed. Claim(s) 1-14 is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction and allowed.	awn from consid			
Applicat	tion Papers				
•	The specification is objected to by the Examination The drawing(s) filed on <u>03 July 2003</u> is/are: a Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct The oath or declaration is objected to by the Barbara and the specific shadows and the specific shadows are specified to be supported to the specific shadows and the specific shadows are specified to be specifi	a) accepted or e drawing(s) be he ection is required if	eld in abeyance. Se the drawing(s) is ob	e 37 CFR 1.85(a). ojected to. See 37 CFR	
Priority	under 35 U.S.C. § 119				
a <u>j</u>	Acknowledgment is made of a claim for foreign All b) Some * c) None of: 1. Certified copies of the priority documents. 2. Certified copies of the priority documents. 3. Copies of the certified copies of the priority application from the International Bure. See the attached detailed Office action for a list.	nts have been re nts have been re iority documents au (PCT Rule 17	eceived. eceived in Applicat have been receiv 7.2(a)).	iion No ed in this National Sta	age
	ce of References Cited (PTO-892)	4)	☐ Interview Summary		
2) 🔲 Noti 3) 🔯 Info	ce of Draftsperson's Patent Drawing Review (PTO-948) rmation Disclosure Statement(s) (PTO-1449 or PTO/SB/0 er No(s)/Mail Date <u>7/3/03</u> .	-,	Paper No(s)/Mail D		i2)

Application/Control Number: 10/613,849 Page 2

Art Unit: 2814

DETAILED ACTION

Claim Objections

1. Claims 11, 12 and 14 are objected to because of the following informalities:

Regarding claims 11 and 12, both claims recite: "the reaction chamber platen".

The correct term should be: $--\underline{a}$ reaction chamber platen--.

Regarding claim 14, line 1 recites: "the method according to claim 3".

The correct dependent should be: -- the method according to claim 13--

Appropriate correction is required.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 2. Claims 1 and 2 are rejected under 35 U.S.C. 102(b) as being anticipated by Ben-Guigui et al. (U.S. Patent No. 5,891,800) of record.

Ben-Guigui teaches a method for forming a transparent inter-metal dielectric as claimed including:

forming a base SiO₂ layer (41);

forming a flowlayer (42) on the base SiO₂ layer (41) by reacting SiH₄ and H₂O₂; and forming a cap SiO₂ layer (44) on the flowlayer (42),

wherein forming the flowlayer (42) includes using a shortened H_2O_2 stabilization time in the range of 30 seconds to approximately 150 seconds. (See Figs. 1-3, col. 1-8).

Note that the stabilization time of Ben-Guigui is between 30 to 150 seconds, which encompasses the claimed limitation of 30 seconds to approximately 50 seconds.

With respect to claim 2, the shortened H_2O_2 stabilization time of Ben-Guigui includes 50 seconds.

3. Claims 9-14 are rejected under 35 U.S.C. 102(b) as being anticipated by Matsuura (U.S. Patent No. 5,985,769).

With respect to claim 9, Matsuura teaches a method for forming a transparent inter-metal dielectric as claimed including:

forming a base SiO₂ layer (3);

forming a flowlayer (4) on the base SiO₂ layer (3) by reacting SiH₄ and H₂O₂; and forming a cap SiO₂ layer (5) on the flowlayer (4),

wherein forming the flowlayer (4) includes using an H_2O_2 deposition pressure in the range of 400 mTorr to approximately 600 mTorr. (See Figs. 1-2).

With respect to claim 10, the H₂O₂ deposition pressure of Matsuura is approximately 500 mTorr (66.65 Pa).

Application/Control Number: 10/613,849

Art Unit: 2814

With respect to claim 11, forming the flowlayer (4) of Matsuura further comprises maintaining the reaction chamber platen (23) at a target value in the range of 0.5 to 3°C.

With respect to claim 12, forming the flowlayer (4) of Matsuura further comprises maintaining the reaction chamber platen (23) at a target value of approximately 1°C.

With respect to claim 13, Matsuura teaches a method for forming a transparent intermetal dielectric as claimed including:

mounting a substrate (1) on a platen (23) in a reaction chamber (21);

forming a base SiO₂ layer (3) over the substrate (1);

forming a flowlayer (4) on the base SiO₂ layer (3) by reacting SiH₄ and H₂O₂; and forming a cap SiO₂ layer (5) on the flowlayer (4),

wherein forming the flowlayer (4) includes maintaining the reaction chamber platen (23) at a target value in the range of 0.5 to 3°C. (See Figs. 1-2).

With respect to claim 14, as best understood by the examiner, the target value of Matsuura is approximately 1°C.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

4. Claims 3-8 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ben-Guigui '800 as applied to claims 1 and 2 above, and further in view of Matsuura '769.

Page 5

With respect to claim 3, Ben-Guigui teaches a method as described in claim 1 above, thus, Ben-Guigui is shown to teach all the features of the claim with the exception of forming the flowlayer at a lower pressure between 400 mTorr to 600 mTorr.

However, Matsuura teaches a method for forming a transparent inter-metal dielectric including: forming a flowlayer (4) comprises using an H₂O₂ at a deposition pressure (of approximately 500 mTorr (66.65 Pa)) which is within the claimed range (400 mTorr to approximately 600 mTorr). (See col. 4, lines 14-35).

Therefore, it would have been obvious to one having ordinary skill in the art at the time of invention to form the flowlayer of Ben-Guigui at the pressure as taught by Matsuura to form an uniform inter-metal layer.

With respect to claim 4, forming the flowlayer in view of Matsuura comprises using an H_2O_2 deposition pressure of approximately 500 mTorr.

With respect to claim 5, forming the flowlayer in view of Matsuura further comprises maintaining the reaction chamber platen at a target value the range of 0.5 to 3°C.

With respect to claim 6, forming the flowlayer in view of Matsuura comprises maintaining the reaction chamber platen at a target value of approximately 1°C.

With respect to claim 7, forming the flowlayer in view of Matsuura further comprises maintaining the reaction chamber platen at a target value in the range of 0.5 to 3°C.

Art Unit: 2814

With respect to claim 8, forming the flowlayer in view of Matsuura further comprises maintaining the reaction chamber platen at a target value of approximately 1 °C.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Anh D. Mai whose telephone number is (571) 272-1710. The examiner can normally be reached on 9:00AM-5:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (571) 272-1705. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Anh D. Mai September 30, 2004